

WHAT IS CLAIMED IS:

1. A multi-layer chip inductive element comprising at least two inductors connected with each other and mounted inside an insulating ceramic material, each of
5 said inductors having a longitudinal axle parallel to the other and having a plurality of conductor patterns and ceramic layers stacked upon one another in sectors, inductive coils of each two adjacent inductors of said inductors being conversely coiled.

2. The multi-layer chip inductive element as defined in claim 1, wherein said
10 conductor patterns of said conductors partially contact each other while stacked upon one another.